

Claims

Sub B
5 1. A semiconductor device comprising:
a semiconductor element having a primary surface and a back
surface, said semiconductor element having an element electrode on the
primary surface; and
10 a circuit board having a primary surface and a back surface, said
circuit board having a board electrode on at least the back surface,
said circuit board having a predetermined opening hole formed therein;
15 wherein the primary surface of said semiconductor element is
bonded to the primary surface of said circuit board by means of an
adhesive layer which is greater in size than the primary surface of
said semiconductor element, and said element electrode of said
semiconductor element is connected to said board electrode provided
on the back surface of said circuit board via said opening hole.

Sub C
20 2. The semiconductor device as according to claim 1, wherein the
surrounding regions of the side surfaces of said semiconductor element
on said circuit board are sealed with resin so as to assume a flange
structure.

25 3. The semiconductor device as according to claim 1, wherein the
surrounding regions of the side surfaces and back surface of said
semiconductor element are sealed with resin.

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